## Silicon N-Channel MOS FET

# **HITACHI**

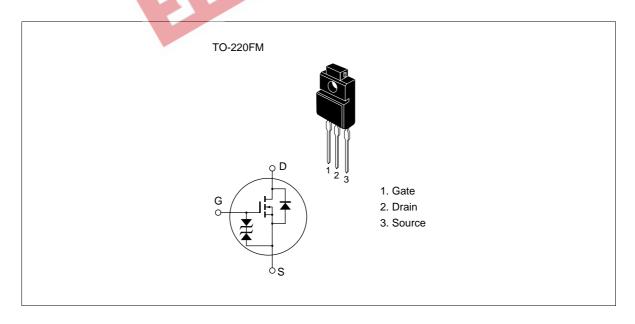
### **Application**

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- T. Com. Cn Suitable for switching regulator and DC-DC converter

#### **Outline**





### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item		Symbol	Ratings	Unit	
Drain to source voltage	2SK1637	$V_{\scriptscriptstyle DSS}$	600	V	
	2SK2422		650		
Gate to source voltage		$V_{\sf GSS}$	±30	V	
Drain current		I <sub>D</sub>	4	Α	
Drain peak current		I <sub>D(pulse)</sub> *1	16	А	
Body to drain diode reverse	I <sub>DR</sub>	4	Α		
Channel dissipation		Pch*2	35	W	
Channel temperature		Tch	150	°C	
Storage temperature		Tstg	-55 to +150	°C	
		N.S.	-33 (0 +130		

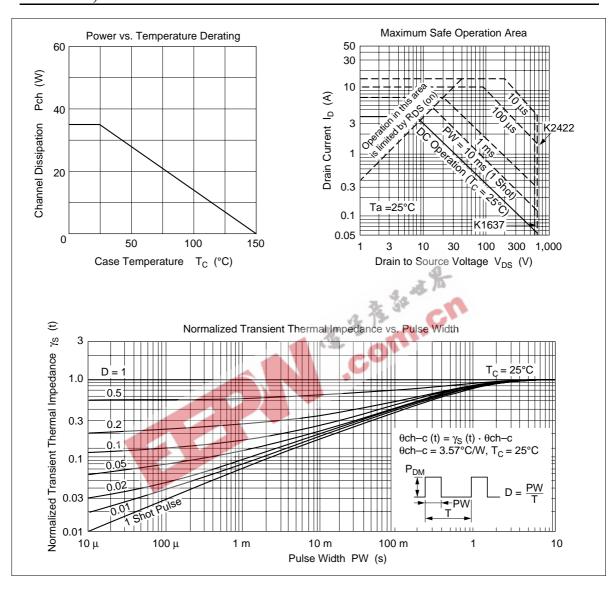


## **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

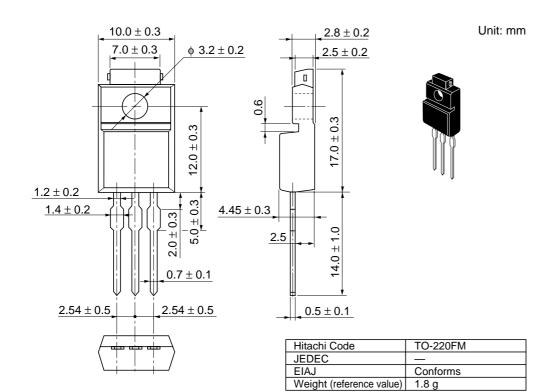
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1637	$V_{(BR)DSS}$	600	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
breakdown voltage	2SK2422	-	650	_			
Gate to source break	down	$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak c	urrent	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage	2SK1637	I <sub>DSS</sub>	_	_	250	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$
drain current	2SK2422	-					$V_{DS} = 550 \text{ V}, V_{GS} = 0$
Gate to source cutoff	voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static Drain to source	2SK1637	R <sub>DS(on)</sub>	_	1.8	2.4	Ω	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
on state resistance	2SK2422		_	2.0	2.6	ک	
Forward transfer adm	ittance	yfs	2.2	3.5	_	S	$I_D = 2 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance		Ciss	_	600	- X	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance		Coss	_	140	3	pF	f = 1 MHz
Reverse transfer capa	acitance	Crss	- 1	25	7.0	pF	-
Turn-on delay time		t <sub>d(on)</sub>	7	8		ns	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time		tr	<del>-)</del> ,	30	_	ns	$R_L = 15 \Omega$
Turn-off delay time		t <sub>d(off)</sub>		60	_	ns	-
Fall time	1	t <sub>f</sub>	_	35	_	ns	-
Body to drain diode for voltage	orward	V <sub>DF</sub>	_	0.9	_	V	$I_F = 4 \text{ A}, V_{GS} = 0$
Body to drain diode re recovery time	everse	t <sub>rr</sub>	_	300	_	ns	$I_F = 4 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note 1. Pulse test

See characteristics curves of 2SK1402, 2SK1402A.







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